





COMPLEMENTARY 15V NPN & 12V PNP LOW SATURATION TRANSISTOR

Features

NPN Transistor

- BV_{CEO} > 15V
- I_C = 4.5A Continuous Collector Current
- Low Saturation Voltage (100mV max @ 1A)
- R_{SAT} = 45mΩ for a low equivalent On-Resistance

PNP Transistor

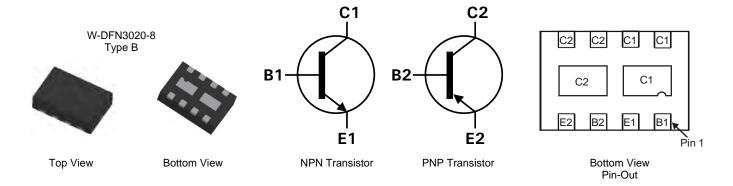
- BV_{CEO} > -12V
- I_C = -4A Continuous Collector Current
- Low Saturation Voltage (-140mV max @ -1A)
- $R_{SAT} = 60 \text{m}\Omega$ for a low equivalent On-Resistance
- h_{FE} characterized up to 12A for high current gain hold up
- Low profile 0.8mm high package for thin applications
- R_{θJA} efficient, 40% lower than SOT26
- 6mm² footprint, 50% smaller than TSOP6 and SOT26
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP capable (Note 4)

Mechanical Data

- Case: W-DFN3020-8 Type B
- Nominal package height: 0.8mm
- Case material: molded plastic. "Green" molding compound.
- UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu, Solderable per MIL-STD-202, Method 208
- Weight: 0.013 grams (approximate)

Applications

- DC DC Converters
- · Charging circuits
- Power switches
- Motor control
- LED Backlighting circuits
- Portable applications



Ordering Information (Note 4 & 5)

Product	Compliance	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
ZXTC6717MCTA	AEC-Q101	DA1	7	8	3,000
ZXTC6717MCQTA	Automotive	DA1	7	8	3,000

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- 2. See http://www.diodes.com for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified.
- 5. For packaging details, go to our website at http://www.diodes.com

Marking Information



DA1 = Product type Marking Code
Dot denotes Pin 1

ZXTC6717MC 1 of 9 October 2012

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Maximum Ratings (@ $T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic	Symbol	NPN	PNP	Unit		
Collector-Base Voltage	V_{CBO}	40	-20	V		
Collector-Emitter Voltage		V_{CEO}	15	-12	V	
Emitter-Base Voltage		V_{EBO}	7	-7	V	
Peak Pulse Current		I _{CM}	15	-12	Α	
Continuous Collector Current	(Notes 6 & 9)	_	1-	4.5	-4	Λ
Continuous Collector Current	(Notes 7 & 9)	IC	5	-4.45	^	
Base Current		l _Β	1		A	

Thermal Characteristics ($@T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic	Symbol	NPN	PNP	Unit	
	(Notes 6 & 9)		1.5 12 2.45 19.6 1.13 8 1.7 13.6		W mW/°C
Power Dissipation	(Notes 7 & 9)				
Linear Derating Factor	(Notes 8 & 9)	P _D			
	(Notes 8 & 10)				
	(Notes 6 & 9)		83.3 51.0 111 73.5		°C/W
The second Decistance I have the Architect	(Notes 7 & 9)				
Thermal Resistance, Junction to Ambient	(Notes 8 & 9)	$R_{\theta JA}$			
	(Notes 8 & 10)				
Thermal Resistance, Junction to Lead (Notes 9 & 11)		$R_{ heta JL}$	17.1]
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +	150	°C	

Notes:

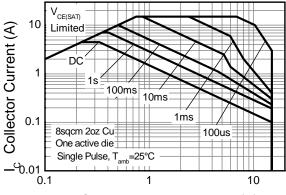
- 6. For a dual device surface mounted on 28mm x 28mm (8cm²) FR4 PCB with high coverage of single sided 2 oz copper, in still air conditions; the device is measured when operating in a steady-state condition. The heatsink is split in half with the exposed collector pads connected to each half.
- 7. Same as note (6), except the device is measured at t <5 sec.

 8. Same as note (6), except the device is surface mounted on 31mm x 31mm (10cm²) FR4 PCB with high coverage of single sided 1oz copper.
- 9. For a dual device with one active die.
- 10. For dual device with 2 active die running at equal power.

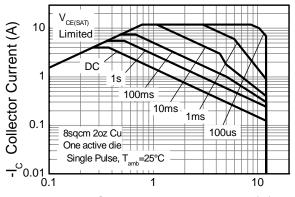
 11. Thermal resistance from junction to solder-point (on the exposed collector pads).



Thermal Characteristics and Derating Information

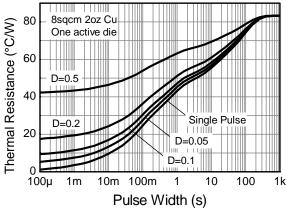


V_{CE} Collector-Emitter Voltage (V)

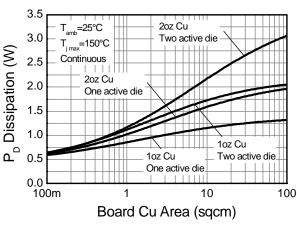


 $-V_{CE}$ Collector-Emitter Voltage (V)

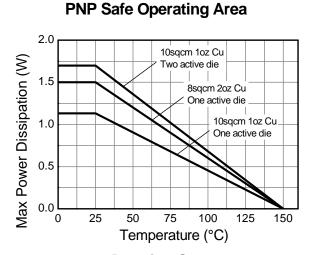
NPN Safe Operating Area



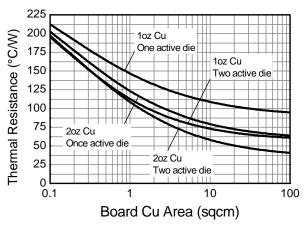
Transient Thermal Impedance



Power Dissipation v Board Area



Derating Curve



Thermal Resistance v Board Area





NPN - Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

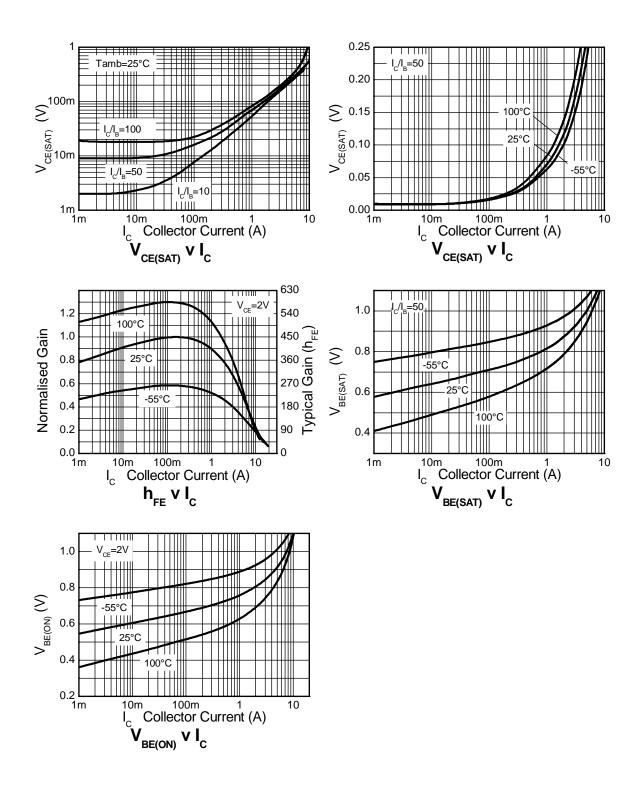
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV _{CBO}	40	70	-	V	$I_{C} = 100 \mu A$
Collector-Emitter Breakdown Voltage (Note 12)	BV _{CEO}	15	18	-	V	$I_C = 10mA$
Emitter-Base Breakdown Voltage	BV _{EBO}	7	8.2	-	V	I _E = 100μA
Collector Cutoff Current	I _{CBO}	-	-	100	nA	V _{CB} = 30V
Emitter Cutoff Current	I _{EBO}	-	-	100	. nA	$V_{EB} = 6V$
Collector Emitter Cutoff Current	I _{CES}	-	-	100	nA	V _{CE} = 12V
Static Forward Current Transfer Ratio (Note 12)	hfE	200 300 200 150	415 450 320 240 80		-	$\begin{split} &I_{C} = 10\text{mA}, \ V_{CE} = 2\text{V} \\ &I_{C} = 200\text{mA}, \ V_{CE} = 2\text{V} \\ &I_{C} = 3\text{A}, \ V_{CE} = 2\text{V} \\ &I_{C} = 5\text{A}, \ V_{CE} = 2\text{V} \\ &I_{C} = 12\text{A}, \ V_{CE} = 2\text{V} \end{split}$
Collector-Emitter Saturation Voltage (Note 12)	V _{CE(sat)}	-	8 70 165 240 200	14 100 200 310	mV	$I_C = 0.1A$, $I_B = 10mA$ $I_C = 1A$, $I_B = 10mA$ $I_C = 3A$, $I_B = 50mA$ $I_C = 4.5A$, $I_B = 50mA$ $I_C = 4.5A$, $I_B = 100mA$
Base-Emitter Turn-On Voltage (Note 12)	$V_{BE(on)}$	-	0.88	0.96	V	$I_C = 4.5A, V_{CE} = 2V$
Base-Emitter Saturation Voltage (Note 12)	V _{BE(sat)}	-	0.94	1.05	V	$I_C = 4.5A, I_B = 50mA$
Output Capacitance	C_obo	-	30	40	pF	V _{CB} = 10V. f = 1MHz
Transition Frequency	f _T	80	120	-	MHz	$V_{CE} = 10V, I_{C} = 50mA,$ f = 100MHz
Turn-on Time	t _{on}	-	120	-	ns	V _{CC} = 10V, I _C = 1A
Turn-off Time	t _{off}	-	160	-	ns	$I_{B1} = I_{B2} = 10 \text{mA}$

Notes: 12. Measured under pulsed conditions. Pulse width \leq 300 μ s. Duty cycle \leq 2%.





NPN - Typical Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)







PNP - Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

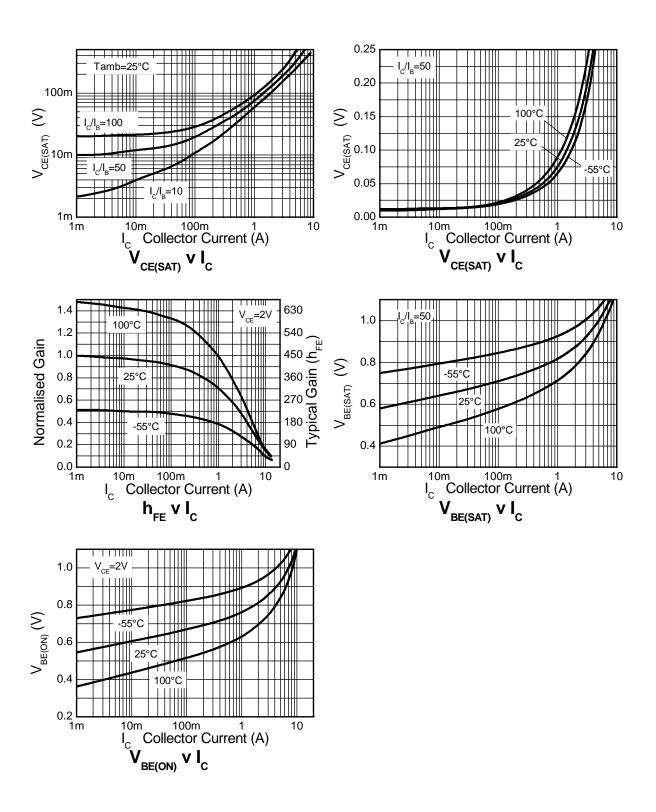
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV _{CBO}	-20	-35	-	V	$I_{C} = -100 \mu A$
Collector-Emitter Breakdown Voltage (Note 12)	BV _{CEO}	-12	-25	-	V	$I_C = -10 \text{mA}$
Emitter-Base Breakdown Voltage	BV _{EBO}	-7	-8.5	-	V	$I_E = -100 \mu A$
Collector Cutoff Current	I _{CBO}	-	-	-100	nA	V _{CB} = -16V
Emitter Cutoff Current	I _{EBO}	-	-	-100	. nA	$V_{EB} = -6V$
Collector Emitter Cutoff Current	I _{CES}	-	-	-100	nA	V _{CES} = -10V
Static Forward Current Transfer Ratio (Note 12)	hFE	300 300 180 60 45	475 450 275 100 70	- - - -	-	I _C = -10mA, V _{CE} = -2V I _C = -100mA, V _{CE} = -2V I _C = -2.5A, V _{CE} = -2V I _C = -8A, V _{CE} = -2V I _C = -10A, V _{CE} = -2V
Collector-Emitter Saturation Voltage (Note 12)	VCE(sat)		-10 -100 -100 -195 -240	-17 -140 -150 -300 -310	mV	$\begin{split} I_C &= -0.1A, \ I_B = -10mA \\ I_C &= -1A, \ I_B = -10mA \\ I_C &= -1.5A, \ I_B = -50mA \\ I_C &= -3A, \ I_B = -50mA \\ I_C &= -4A, \ I_B = -150mA \end{split}$
Base-Emitter Turn-On Voltage (Note 12)	V _{BE(on)}	-	-0.87	-0.96	V	$I_C = -4A$, $V_{CE} = -2V$
Base-Emitter Saturation Voltage (Note 12)	V _{BE(sat)}	-	-0.97	-1.07	V	$I_C = -4A$, $I_B = -150mA$
Output Capacitance	C _{obo}	-	21	30	pF	V _{CB} = -10V. f = 1MHz
Transition Frequency	f _T	100	110	-	MHz	V _{CE} = -10V, I _C = -50mA, f = 100MHz
Turn-on Time	t _{on}	-	70	-	ns	$V_{CC} = -6V, I_{C} = -2A$
Turn-off Time	t _{off}	-	130	-	ns	$I_{B1} = I_{B2} = -50 \text{mA}$

Notes: 12. Measured under pulsed conditions. Pulse width \leq 300 μ s. Duty cycle \leq 2%.





PNP - Typical Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

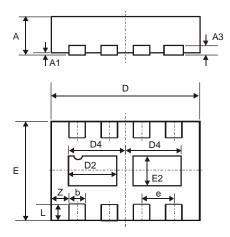






Package Outline Dimensions

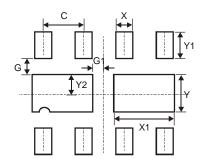
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



W-DFN3020-8						
Type B						
Dim	Min	Max	Тур			
Α	0.77	0.83	0.80			
A1	0	0.05	0.02			
А3	-	-	0.15			
b	0.25	0.35	0.30			
D	2.95	3.075	3.00			
D2	0.82	1.02	0.92			
D4	1.01	1.21	1.11			
е	-	-	0.65			
Е	1.95	2.075	2.00			
E2	0.43	0.63	0.53			
L	0.25	0.35	0.30			
Z	-	-	0.375			
All Dimensions in mm						

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
C	0.650
G	0.285
G1	0.090
Х	0.400
X1	1.120
Υ	0.730
Y1	0.500
Y2	0.365





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